

Price Revision of Epoxy Resin Molding Compounds for Encapsulation of Semiconductor Devices SUMIKON™ EME

Sumitomo Bakelite Co., Ltd. (Headquarters: Shinagawa-ku, Tokyo; President and Representative Director: Shinichi Kajiya) hereby announces a revision to the sales prices of its Epoxy Resin Molding Compounds for Encapsulation of Semiconductor Devices (hereinafter referred to as "SUMIKON™ EME").

Due to the recent situation in the Middle East, procurement costs for raw materials used in SUMIKON™ EME have increased. In addition, costs for packaging materials, energy, and transportation continue to rise, further increasing overall product costs.

While we have been prioritizing the securing of raw materials and the continuation of production to ensure a stable supply to our customers, the impact of these cost increases has exceeded the level that can be absorbed through our own efforts, making it extremely difficult to maintain current prices.

Accordingly, we have decided to request our customers' understanding regarding a revision of product prices as outlined below.

1. Products Subject to Price Revision

- Epoxy Resin Molding Compounds for Encapsulation of Semiconductor Devices
SUMIKON™ EME (all grades)

2. Price Revision Rate

Approximately 10% to 20% increase from current prices

3. Effective Date of Price Revision

Shipments made on or after June 1, 2026

Please note that the details of this revision may be subject to change in response to significant fluctuations in costs such as raw materials, auxiliary materials, and logistics.

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